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CONFIRMATION NO. 6221

Bib Data Sheet

<b>SERIAL NUMBER</b> 10/525,996	<b>FILING OR 371(c) DATE</b> 02/28/2005 <b>RULE</b>	<b>CLASS</b> 257	<b>GROUP ART UNIT</b> 2811	<b>ATTORNEY DOCKET NO.</b> 1217-050618
<b>APPLICANTS</b> Hideo Senoo, Saitama, JAPAN; Koichi Nagamoto, Saitama, JAPAN; Katsuhiko Horigome, Saitama, JAPAN; Hitoshi Ohashi, Saitama, JAPAN;				
<b>** CONTINUING DATA *****</b> This application is a 371 of PCT/JP03/10570 08/21/2003				
<b>** FOREIGN APPLICATIONS *****</b> JAPAN 2002-249622 08/28/2002				
Foreign Priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions <input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after met Allowance Verified and Acknowledged <u>Examiner's Signature</u> <u>Initials</u>		<b>STATE OR COUNTRY</b> JAPAN	<b>SHEETS DRAWING</b> 2	<b>TOTAL CLAIMS</b> 20
				<b>INDEPENDENT CLAIMS</b> 5
<b>ADDRESS</b> Kent E Baldauf 436 Seventh Avenue 700 Koppers Building Pittsburgh , PA 15219-1818				
<b>TITLE</b> Protective structure of semiconductor wafer, method for protecting semiconductor wafer, multilayer protective sheet used therein, and method for processing semiconductor wafer				
<b>FILING FEE RECEIVED</b> 1300	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue ) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit	